

Title (en)

METHOD OF MAKING A CEMENTED CARBIDE POWDER WITH LOW SINTERING SHRINKAGE AND THE POWDER OBTAINED

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES ZEMENTKARBIDPULVERS MIT GERINGER SINTERUNGSSCHRUMPUNG UND IN DEM VERFAHREN HERGESTELLTES PULVER

Title (fr)

PROCÉDÉ DE FABRICATION D'UNE POUDRE DE CARBURE CÉMENTÉ AVEC UN RETRAIT AU FRITTAGE FAIBLE, ET POUDRE OBTENUE

Publication

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Application

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Priority

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Abstract (en)

[origin: WO2009041901A1] 6 Abstract The present invention relates to a method of making cemented carbide powder with low sintering shrinkage comprising WC and 4- 15 wt-% Co and up to 20 wt-% cubic carbide forming elements from the Groups 4b and 5b of the Periodic Table of the Elements by 5 means of the powder metallurgical techniques wet milling, press- ing and sintering. According to the method wet milling is performed in a rotating ball mill with a ratio between the weight of milling bodies and powder of 2-5. The milling bodies are shaped either as spheres or cylinders with semi-spherical end 10 surfaces. The spherical bodies have a diameter of 10 to 15 mm and the cylindrical bodies have a diameter and height of 10 to 15 mm. The composition of the milling bodies is WC with 6 to 10 wt-% Co. The present invention also relates to a powder made according 15 to the method.

IPC 8 full level

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